

In the Claims:

Claims 1 - 17 (canceled).

Claim 18 (currently amended): An electronic package, comprising:

a substrate having at least two electrical contacts thereon; and

a passive SMD having at least one electrical contact at each end thereof ~~two electrical contacts~~ respectively bonded by a solder connection to ~~the said at least two~~ electrical contacts on said substrate, said passive SMD encapsulated by a noflow resin such that the space between said passive SMD and said substrate is filled with said resin and said resin forms fillets around said at least one electrical contact at each end thereof and said passive SMD solder connection.

Claim 19 (currently amended): The package as set forth in Claim 18 wherein said passive SMD is a capacitor device having two electrical contacts with each contact having more than one contact surface at said each end thereof and with the said solder connection for each electrical contact in contact with said more than one contact surface.

Claim 20 (currently amended): The package as set forth in Claim 19 wherein said noflow resin is formed from an epoxy-based flux encapsulant with flux combined into a one part epoxy system.

Claim 21 (currently amended): An electronic package, comprising:

a substrate having at least two electrical contacts thereon; and

a passive SMD having at least two electrical contacts each having at least a lower electrical contact ~~surface portion~~ and an upper electrical contact surface at the terminus thereof ~~portion~~ with at least said lower electrical contact ~~portion~~ surface of said at least two electrical contacts of said passive SMD respectively positioned toward said at least two electrical contacts of said substrate and with said at least said lower electrical contact ~~portion~~ surface and said upper electrical contact ~~portion~~ surface at the terminus thereof of said at least two electrical contacts each respectively bonded by a solder connection to the said at least two electrical contacts on said substrate such that said upper contact surface is covered by said solder connection , said passive SMD encapsulated by a resin such that the space between said passive SMD and said substrate is filled with said resin and with said resin further forming fillets around each said passive SMD solder connection including forming fillets covering said solder connection covering said upper contact surface.

Claim 22 (previously presented): The package as set forth in Claim 21 wherein said resin is formed from an epoxy-based flux encapsulant with flux combined into a one part epoxy system.

Claim 23 (canceled)

Claim 24 (canceled)